Sensors and Materials


Call for Papers

This special issue of Sensors and Materials aims to focus on bioelectronics, biosensors, biomedical devices, Bio-MEMS/NEMS and Sensing Biology with a strong emphasis on commercialization and applications. All articles related to these technology and applications are welcome.

Scope:
- Bio Sensors
  - Lab-on-chip
  - Miniaturized diagnostic
  - Novel bioelectric sensing
  - Nanophotonics/THz Sensing
  - Physiological monitoring
- Bio Electronics
  - Biomedical signal processing
  - Body area sensor networks
  - Circuits for biomedical applications/devices
  - Flexible electronics
  - Implantable electronics
- BioMedical devices
  - Bio-imaging technology
  - Bio-compatible materials and packaging
  - Implantable medical devices
  - Prosthesis and Neural probes
  - Surgical robots
- BioMEMS/NEMS
  - Drug delivery
  - Energy harvesting technology
  - MEMS/NEMS for biomedical applications
  - Microfluidics for biomedical applications
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Guest Editors: Prof. Masaya Miyazaki (Kyushu University) and Assistant. Prof. Hirofumi Nogami (Kyushu University)
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If you have any questions, please feel free to contact the editorial staff at the address below.

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